

**DECLARATION  
AND POWER OF ATTORNEY  
U.S.A.**

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ATTORNEYS' DOCKET NO.

P67358US0

ALL PATENTS, INCLUDING DESIGN  
FOR APPLICATION BASED ON PCT, PARIS CONVENTION;  
NON PRIORITY; OR PROVISIONAL APPLICATIONS

As a below named inventor, I declare that my residence, post office address and citizenship are stated below next to my name, the information given herein is true, that I believe that I am the original, first and sole inventor (if only one name is listed at 201 below), a first and joint inventor (if plural inventors are named below at 201-203, or on additional sheets attached hereto) of the subject matter which is claimed and for which patent is sought on the invention entitled:

SEMICONDUCTOR DEVICE CAPABLE OF PREVENTING CORROSION OF METAL WIRES FROM  
CMP (CHEMICAL MECHANICAL POLISHING) PROCESS

which is described and claimed in:

☒ the attached specification

☐ PCT International Application No. \_\_\_\_\_ filed \_\_\_\_\_

☐ the specification in application Serial No. \_\_\_\_\_ filed \_\_\_\_\_

(if applicable) and amended on \_\_\_\_\_

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a)-(b) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

<u>2000-80891</u>	<u>Republic of Korea</u>	<u>22/12/2000</u>
(Number)	(Country)	(Day/Month/Year Filed)
_____	_____	_____
(Number)	(Country)	(Day/Month/Year Filed)
_____	_____	_____
(Number)	(Country)	(Day/Month/Year Filed)

Priority Claimed

☒ Yes ☐ No

☐ Yes ☐ No

☐ Yes ☐ No

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

Application No. \_\_\_\_\_ Filing Date \_\_\_\_\_ Application No. \_\_\_\_\_ Filing Date \_\_\_\_\_

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

(Application Serial No.)

(Filing Date)

(Status: patented, pending, abandoned)

**POWER OF ATTORNEY:** As a named inventor, I hereby appoint the following attorneys(Registration No.) to prosecute this application, receive and act on instructions from my agent, and transact all business in the Patent and Trademark Office connected therewith. HARVEY B. JACOBSON, JR.(20,851); D. DOUGLAS PRICE (24,514); JOHN CLARKE HOLMAN (22,769); MARVIN R. STERN (20,640); MICHAEL R. SLOBASKY (28,421); JONATHAN L SCHERER (29,851); IRWIN M. AISENBERG (19,007); WILLIAM E. PLAYER (31,409); and YOON S. HAM (45,307)

SEND CORRESPONDENCE TO:

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**JACOBSON, PRICE, HOLMAN & STERN**  
PROFESSIONAL LIMITED LIABILITY COMPANY

\* Inventor(s) name must include at least one unabbreviated first or middle name.

201	FULL NAME* OF INVENTOR	FAMILY NAME	GIVEN NAME		MIDDLE NAME
		<b>KIM</b>	<b>HYUNG-JUN</b>		
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	POST OFFICE ADDRESS	POST OFFICE ADDRESS		CITY	STATE OR COUNTRY
					ZIP CODE
203	FULL NAME* OF INVENTOR	FAMILY NAME	GIVEN NAME		MIDDLE NAME
	RESIDENCE & CITIZENSHIP	CITY	STATE OR FOREIGN COUNTRY		COUNTRY OF CITIZENSHIP
	POST OFFICE ADDRESS	POST OFFICE ADDRESS		CITY	STATE OR COUNTRY
					ZIP CODE

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under section 1001 of Title 18 of the United States Code; and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

SIGNATURE OF INVENTOR 201*	SIGNATURE OF INVENTOR 202*	SIGNATURE OF INVENTOR 203*
DATE <u>12.17.2001</u>	DATE	DATE